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IC CARD AND PRODUCTION THEREOF

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Abstract

PURPOSE:To enhance the mechanical strength of a card base without increasing the thickness of the card base, by a construction wherein the bottom surface of a recessed part of the card base for inserting a module therein is provided with a step between a central part and a peripheral part so that the central part is deeper than the peripheral part.

CONSTITUTION:A recessed part 3b of a card base 3 for inserting a module 2 therein is provided with a step between the bottom surface 6 of a central part and the bottom surface 5 of a peripheral part so that the material thickness of the card base 3 is greater at the bottom surface 5 than at the bottom surface 6. The module 2, having a flat bottom surface, is inserted in the opening part thus obtained, and is adhered to and fixed by the bottom surface 6 of the central part of the recessed part. In this IC card, the thickness of the bottom surface of the card base for inserting the module therein and the thickness of the module incorporating an IC therein are increased without changing the total thickness of the IC card. By this, mechanical strength of the card base and that of the module can be enhanced, the IC is protected, the card base is prevented from being damaged, and durability to bending is enhanced.

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